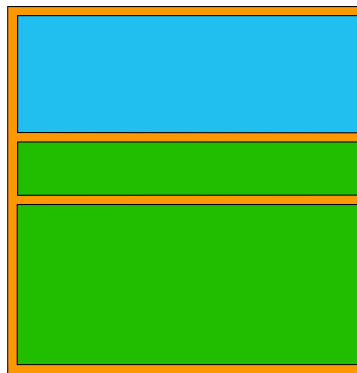
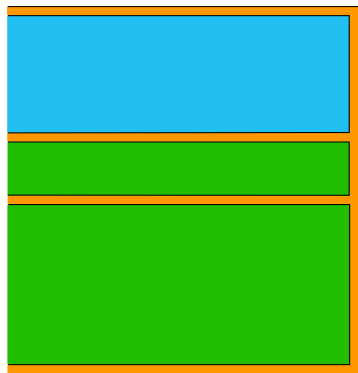


# PCB Layer Stack-up

Through via  
Via1234



Top silk screen

Top solder resist

Top 0.5 oz Cu + Au plating

20 mil (0.51 mm) Rogers RO4350B

0.5 oz Cu

8 mil (0.2 mm) FR4 prepreg

0.5 oz Cu

30 mil (0.76 mm) FR4 core

Bottom 0.5 oz Cu + Au plating

Bottom solder resist

Bottom silk screen